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# Offset-electrode profile acquisition strategy for electrical resistivity tomography

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## Abstract

We present an electrode layout strategy that allows electrical resistivity profiles to image the third dimension close to the profile plane. This “offset-electrode profile” approach involves laterally displacing electrodes away from the profile line in an alternating fashion and then inverting the resulting data using three-dimensional electrical resistivity tomography software. In our synthetic and field surveys, the offset-electrode method succeeds in revealing three-dimensional structures in the vicinity of the profile plane, which we could not achieve using three-dimensional inversions of linear profiles. We confirm and explain the limits of linear electrode profiles through a discussion of the three-dimensional sensitivity patterns: For a homogeneous starting model together with a linear electrode layout, all sensitivities remain symmetric with respect to the profile plane through each inversion step. This limitation can be overcome with offset-electrode layouts by breaking the symmetry pattern among the sensitivities. Thanks to freely available powerful three-dimensional resistivity tomography software and cheap modern computing power, the requirement for full three-dimensional calculations does not create a significant burden and renders the offset-electrode approach a cost-effective method. By offsetting the electrodes in an alternating pattern, as opposed to laying the profile out in a U-shape, we minimize shortening the profile length.

*Keywords:* Electrical resistivity tomography; 2-D profiles; 3-D inversion; Sensitivity pattern; Field method

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## 1. Introduction

Over the past few decades, electrical resistivity tomography (ERT) has been among the most popular geophysical methods for imaging the shallow subsurface. Its versatility has made it a viable technique for applications as diverse as aquifer characterization (e.g. Slater et al., 2000; Kemna et al., 2002; Coscia et al., 2011, 2012; Doetsch et al., 2010, 2012; Yeh et al., 2015), contamination monitoring (e.g. Ogilvy et al., 2003; Olofsson et al., 2006; Genelle et al., 2012; Bichet et al., 2016; Maurya et al., 2017), bedrock mapping (e.g. Cardarelli & De Donno, 2017; Chambers et al., 2012, 2013), soil science (see Samouëlian et al., 2005, for an overview), subsurface cavity detection (Leucci, 2006; Lazzari et al., 2010; Martínez-Pagán et al., 2013; Park et al., 2014; Bharti et al., 2016), landslide (e.g. Ling et al., 2016; Wilkinson et al., 2016) and rock avalanche investigations (e.g. Socco et al., 2010), studies of saline intrusion (Martínez et al., 2009; Goebel et al., 2017), volcanology (Revil, 2008; Barde-Cabusson et al., 2013; Brothelande et al., 2014), and archaeology (Astin et al., 2007; Ullrich et al., 2007; Negri et al., 2008; Himi et al., 2016; Nero et al., 2016). Loke et al. (2013) provide an overview covering recent electrical resistivity tomography developments.

Freely available high-performance software packages for electrical resistivity tomography such as BERT (Günther et al., 2006; Rücker et al., 2006) and E4D (Johnson et al., 2010),

cheap computing power, and improvements in algorithm design (e.g. Blome et al., 2009; Papadopoulos et al., 2011; Plattner et al., 2010, 2012) have made three-dimensional electrical resistivity data inversions cheaper than ever. Nevertheless, two-dimensional investigations imaging resistivity at depth along profile lines remain the most widely used electrical resistivity applications (Loke et al., 2013). The popularity of two-dimensional over three-dimensional surveys is likely a consequence of reduced equipment requirements and lower cost of work in the field. Developments in data acquisition strategies (e.g. Blome et al., 2011; Hoorde et al., 2017) and of the equipment itself (e.g. Stummer et al., 2002; Blome et al., 2011) help offset some of the extra cost of three-dimensional surveys in the field, but are unlikely to bridge the vast gap between the simplicity of two-dimensional profiles and the time required to set up and run a full 3-D array. To obtain subsurface resistivity models along profile lines, investigators typically make use of a “2.5-D” inversion procedure (Dey & Morrison, 1979), which implements a three-dimensional current source but assumes that subsurface resistivities only vary within the profile plane and infinitely extend perpendicular to the plane. These 2.5-D inversions allow for a quick imaging of the subsurface along profile lines but are prone to artifacts and unable to image resistivity variations beyond the profile plane.

We propose a cost-effective profile approach that has the capability of imaging the third dimension close to the profile plane. As we show in Section 3, simply inverting linear profile data using three-dimensional software does not suffice. Our approach involves staggering the electrodes on the surface sur-

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